

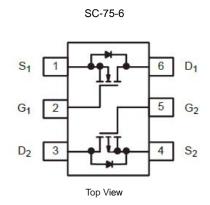
## Si1035X-T1-GE3-VB Datasheet N-and P-Channel 20V (D-S) MOSFET

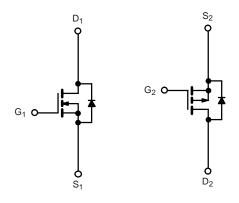
PRODUCT SUMMARY					
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
N-Channel	20	0.270 at V <sub>GS</sub> = 4.5 V	0.60		
N-Channel		0.410 at V <sub>GS</sub> = 2.5 V	0.55		
P-Channel	- 20	0.660 at V <sub>GS</sub> = - 4.5 V	- 0.30		
		0.840 at V <sub>GS</sub> = - 2.5 V	- 0.25		

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	- 20	V	
Gate-Source Voltage		$V_{GS}$	± 20	± 20		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	0.6	- 0.3		
	T <sub>A</sub> = 70 °C		0.55	- 0.25		
Pulsed Drain Current		I <sub>DM</sub>	3	- 2	А	
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	1.05	- 1.05		
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 25 °C	D	1.15		W	
	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.73		V V	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	R <sub>thJA</sub>	93	110	°C/W	
	Steady State		130	150		
Maximum Junction-to-Lead	Steady State	R <sub>thJL</sub>	75	90		

a. Surface Mounted on FR4 board.

b.  $t \le 5$  s.



Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Static								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ N-C		0.7			V	
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 0.8			V	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V	N-Ch P-Ch			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V	N-Ch			± 100		
		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$ N-C				- 1	μA	
						5		
		V <sub>DS</sub> = - 24 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	P-Ch			- 5		
On-State Drain Current <sup>a</sup>	_	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	N-Ch	3.7			А	
	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	P-Ch	- 3				
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$	N-Ch	0.410				
	В	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 0.3A P-			0.840			
	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{A}$	N-Ch		0.270		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.3 A	P-Ch		0.660			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	N-Ch		4.3		S	
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 1.8 A	P-Ch		2.4		s	
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 1.05 A, V <sub>GS</sub> = 0 V	N-Ch		0.81	1.10	V	
Diode i diward voltage		I <sub>S</sub> = - 1.05 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.83	- 1.10		
Dynamic <sup>b</sup>								
Total Gate Charge	Qg	N-Channel	N-Ch		2.1	3.2	nC	
	9	$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 1.8 \text{ A}$	P-Ch N-Ch		2.4	3.6		
Gate-Source Charge	$Q_{gs}$		P-Ch		0.7 0.9			
	_	P-Channel V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 5 V, I <sub>D</sub> = - 1.8 A	N-Ch		0.7			
Gate-Drain Charge	$Q_{gd}$	VDS = 113 V, VGS = 13 V, ID = 11.0 A	P-Ch		0.8			
Gate Resistance	R <sub>g</sub>		N-Ch	0.5		2.4	Ω	
Oale Neoloidille			P-Ch	3		11	34	
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel	N-Ch		7	11		
		$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$	P-Ch N-Ch		8	12 14		
Rise Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$	P-Ch		12	18		
Turn-Off Delay Time Fall Time	t <sub>d(off)</sub>	P-Channel	N-Ch		13	20	1	
		$V_{DD} = -15 \text{ V}, R_L = 15 \Omega$	P-Ch		12	18	ns	
	t <sub>f</sub>	$I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 6 \Omega$	N-Ch		5	8		
	٦	F			7	11	-	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 1.05 A, dI/dt = 100 A/µs N-0			35	60		
		$I_F = -1.05 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$	P-Ch		30	60		

#### Notes:

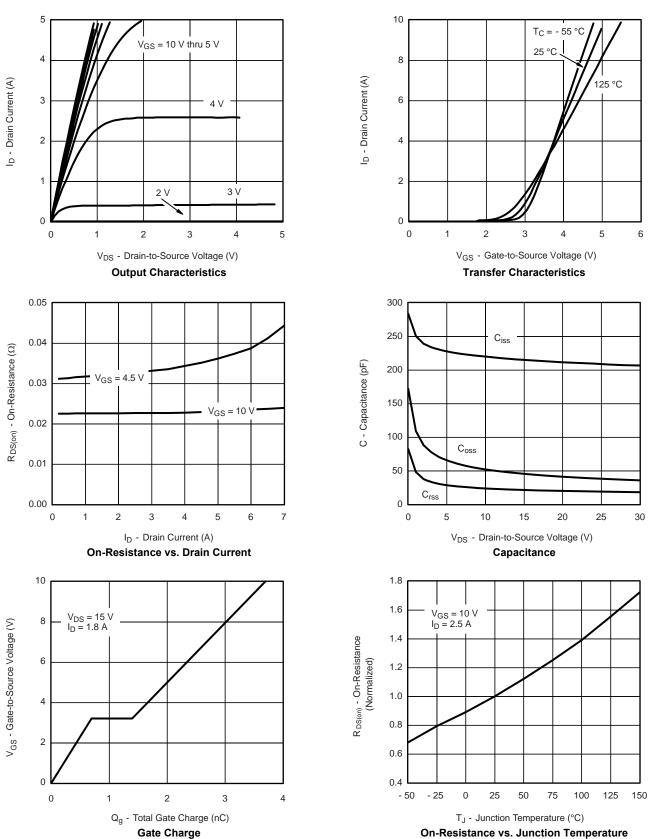
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.



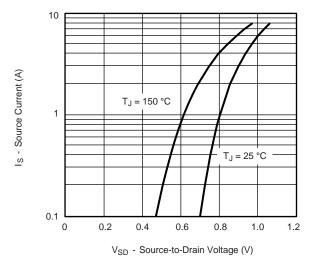
### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



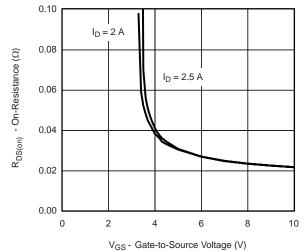
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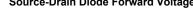
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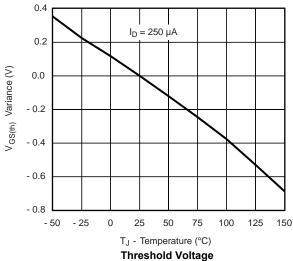


Source-Drain Diode Forward Voltage



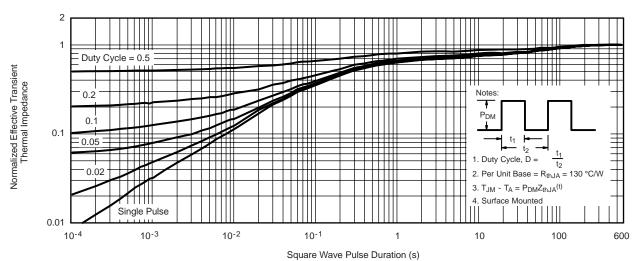
On-Resistance vs. Gate-to-Source Voltage





8 6 4 2 0 0 0.01 0.1 1 10 30 Time (s)

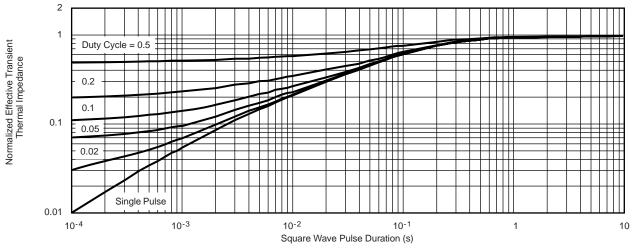
Single Pulse Power (Junction-to-Ambient)



Normalized Thermal Transient Impedance, Junction-to-Ambient

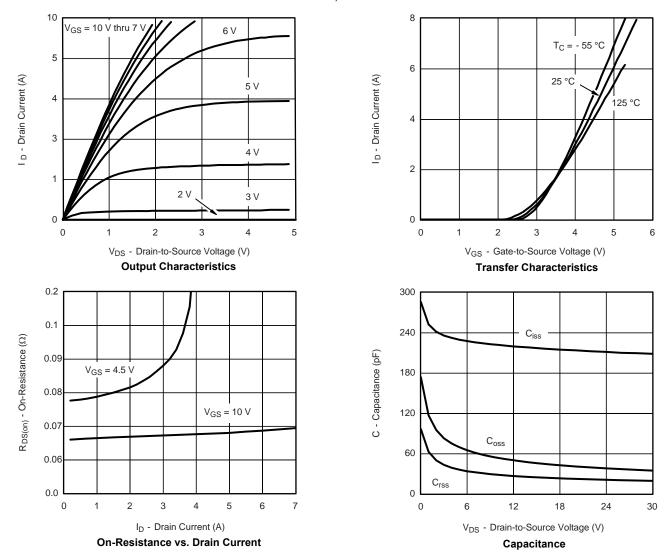


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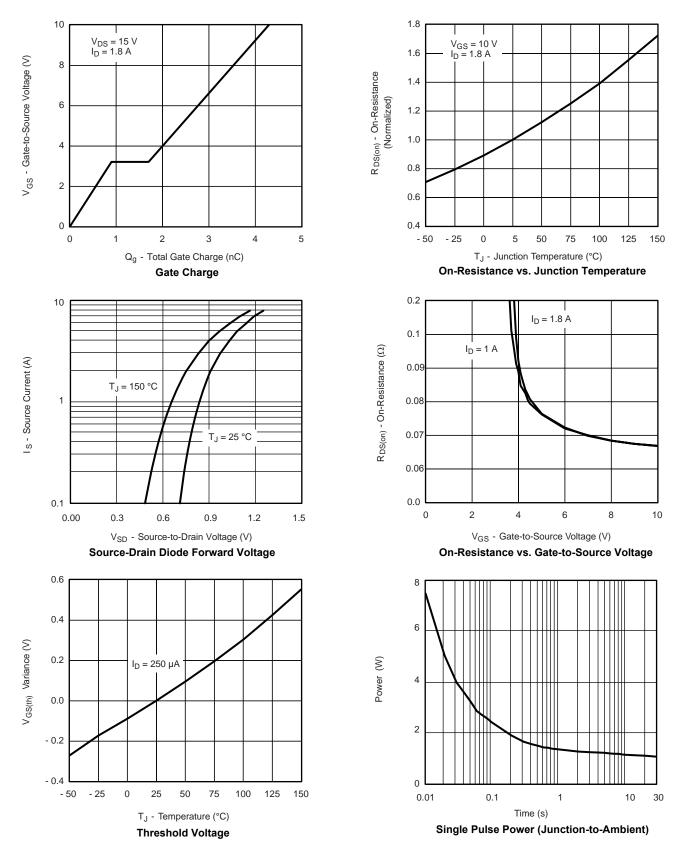
Normalized Thermal Transient Impedance, Junction-to-Foot

#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





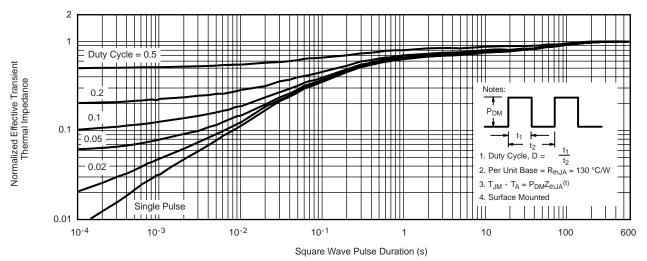
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



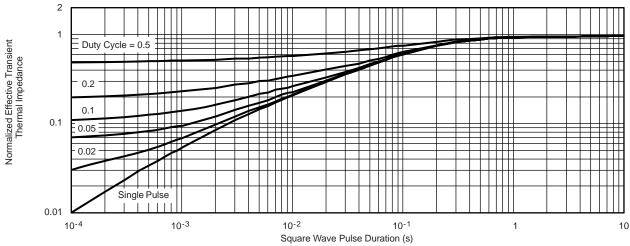
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#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



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